



BSI Standards Publication

Device embedding assembly technology

Part 2-602: Guideline for stacked electronic module — Evaluation
method of inter-module electrical connectivity

National foreword

This British Standard is the UK implementation of EN IEC 62878-2-602:2021. It is identical to IEC 62878-2-602:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Amendments/corrigenda issued since publication

Date	Text affected
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English Version

Device embedding assembly technology - Part 2-602: Guideline
for stacked electronic module - Evaluation method of inter-
module electrical connectivity
(IEC 62878-2-602:2021)

Techniques d'assemblage avec appareil(s) intégré(s) -
Partie 2-602: Lignes directrices pour un empilement de
modules électroniques - Méthode d'évaluation de la
connectivité électrique entre modules
(IEC 62878-2-602:2021)

Montageverfahren für eingebettete Bauteile - Teil 2-602:
Leitfaden für gestapelte Elektronikmodule - Verfahren zur
Beurteilung der elektrischen Verbindungsfähigkeit zwischen
den Modulen
(IEC 62878-2-602:2021)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 91/1663/CDV, future edition 1 of IEC 62878-2-602, prepared by IEC/TC 91 “Electronics assembly technology” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62878-2-602:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-04-27
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-07-27

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Endorsement notice

The text of the International Standard IEC 62878-2-602:2021 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and-assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies		-

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